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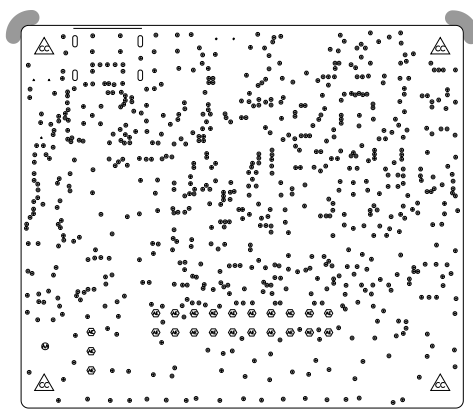
D

DESIGN CROSS SECTION CHART

TOTAL THICKNESS 1.6 MM

L1: TOP CONDUCTOR - COPPER + PLATING 0.035 MM  
\* DIELECTRIC - FR-4 0.175 MM (TOP PRIORITY)  
L2: L2 PLANE - COPPER 0.035 MM  
  
\* DIELECTRIC - FR-4 1.11 MM  
  
L3: L3 PLANE - COPPER 0.035 MM  
\* DIELECTRIC - FR-4 0.175 MM  
L4: BOTTOM CONDUCTOR - COPPER + PLATING 0.035 MM

Milling tool 2.0 mm TYP



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	FINISHED_SIZE	ROTATION	PLATED	QTY
.	0.2	-	PLATED	701
•	1.05	-	PLATED	23
•	1.1	-	PLATED	1
△	3.2	-	PLATED	4
.	0.899	-	NON-PLATED	2
.	1.0	-	NON-PLATED	3
0	1.4x0.6	90.000	PLATED	2
0	1.5x0.6	90.000	PLATED	2

TEXAS INSTRUMENTS

DRILLLP-XDS110ETRev. B

DATE: 2022-09-29

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

DESIGN INFORMATION

MIN. TRACK WIDTH: 0.15 mm  
MIN. CLEARANCE: 0.15 mm  
MIN. VIA PAD SIZE: 0.40 mm  
  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/-150 um, HOLES +/-80 um  
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/-80 um

MATERIAL:  
☒ FR-4 ☐ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 1.6mm +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2 ☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2 ☐ OTHER +/-  
  
DRILLING:  
REFERENCE: ☐ AS SHOWN ☒ NC\_DRILL FILES  
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER  
  
BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SILKSCREEN RESIST COLOR: ☐ GREEN ☒ OTHER RED  
☒ MATTE ☐ SEMI-GLOSS  
  
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER  
  
ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☒ V. SCORE  
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ RoHS ☐ OTHER PER ORDER  
  
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
PCB MUST BEAR THE UL94V-0 UL REG. MATERIAL ID NUMBER: BOTTOM LAYER  
ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☒ NONE ☐ REQUIRED ☐ PER ORDER  
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE  
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE  
☐ OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE  
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE  
☐ TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

TITLE:  
LP-XDS110ET

PROJECT NUMBER:  
MCU101

FILE NAME:  
LP-XDS110ET.brd

DESIGNER:  
RGW

DATE:  
2022-09-29

REVISION:  
B

SCALE: 1.00

ALLEGRO DESIGNER VERSION:  
17.2

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